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(54) FILM-SHAPED ADHESIVE FOR ELECTROLESS PLATING AND MANUFACTURE OF PRINTED WIRING BOARD USING THE SAME

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a film-shaped adhesive for electroless plating in which the adhesion of deposited electroless plating metal is satisfactory.

SOLUTION: A deposition face has a rough face whose mean roughness is 1-10 μ m. A film-shaped adhesive for electroless formed on the rough face of a carrier film on which a rough face whose DIN mean roughness is 1-10 μ m is formed is integrally laminated on a board, so that the film-shaped adhesive for electroless plating can be brought into contact with the board while it is accompanied with the carrier film. Then, the carrier film is removed so that a laminated board with the adhesive for electroless plating can be obtained. This is provided for manufacturing a printed wiring board by an additive method.

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